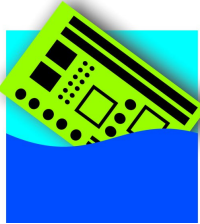


VIGON® A 200⁺

Water-based defluxing agent for low pressure cleaning processes



VIGON® A 200⁺ was specifically developed for low and medium pressure spray-in-air processes with long exposure times. VIGON® A 200⁺ is a MPC® based cleaning agent recommended for removing a wide range of flux residues from electronic assemblies. VIGON® A 200⁺'s mild formula is particularly gentle on all solder joints and materials.

Areas of application: PCB cleaning		Further information for this product:
Low solid flux residues	++	Technical Information Sheet 2: Removability overview list
Rosin based flux residues	++	Technical Information Sheet 3: Material compatibility overview
Water soluble flux residues	++	Application Recommendation: Initial process parameters recommendation
Solder paste (unsoldered)	+	
SMT or conductive adhesives	o	MPC® Technology Sheet: Detailed information on the MPC® Technology

++ highly recommended, best results

+ recommended

o possible

Cleaning trials in ZESTRON's Technical Centers

Free of charge cleaning trials can be performed at one of ZESTRON's global Application Technology Centers. ZESTRON's American, European and Asian Technology Centers feature spray-in-air, ultrasonic and spray-under-immersion processes. This provides for an extensive overview on all available processes by leading equipment manufacturers and offers the user a unique testing opportunity. Please consult with ZESTRON's Application Technology Centers on future cleaning trials.

Advantages over other cleaners:

- Specifically developed for batch cleaning applications.
- Ability to remove a wide range of flux residues.
- Excellent material compatibility even with long contact times.
- High bath loading capacity ensures extended bath life, low maintenance costs and reduced costs per cleaned part.
- Surfactant-free formulation eliminates the formation of white residues on cleaned parts and cleaning equipment and eliminates time-consuming surfactant monitoring.
- Mild formulation results in shiny solder points and low ionic contamination.
- Does not foam, even in high pressure applications.

Please check material compatibility and refer to the material compatibility list, before cleaning plastics.

Process	Cleaning	Rinsing	Drying
Spray-in-air	VIGON® A 200+	DI-water	Hot air or circulating air
Centrifugal Cleaning	VIGON® A 200+	DI-water	Hot air or circulating air

Technical Data		
Please note that the information above represents VIGON® A 200+ at a 15 % concentration.		
Density	(g/ccm) at 20°C/68°C	1
Surface tension	(mN/m) at 25°C/77°F	31.7
Boiling range	°C/°F	> 100 / 212
Flash point	°C/°F	None
pH-Value	10g/l H ₂ O	9.9
Vapor pressure	(mbar) bei 20°C/68°F	20
Cleaning temperature	°C/°F	40 – 60 / 104 - 140
Solubility in water		Soluble
Application concentration	%	15 - 20
HMIS Rating	Health, Flammability, Reactivity	1 – 0 – 0

Lead-free Compliant:



VIGON® A 200+ meets the new RoHS & WEEE guidelines as well as current worker safety standards and the actual applicable environmental requirements. Its formulation is free of any other banned hazardous substances.



Extensive lead-free defluxing with VIGON® A 200+ was successfully completed by our Application Technology Centers. For further details please check our Technical Information Sheet 2.

Environmental, health and safety regulations:

VIGON® A 200+ is water-based and biodegradable. The cleaning agent does not contain any halogenated compounds and is not considered a hazardous material. No special precaution is required in the handling of the VIGON® A 200+.

Availability/Storage:

VIGON® A 200+ is available as concentrate in 1L bottles, 5L and 25L plastic canisters or 200L drums. Store VIGON® A 200+ in the original container in a temperature between 41- 86°F / 5 - 30°C. The product has a minimum shelf life of 5 years in factory sealed containers.

Cleaning Standards:

Cleaning with VIGON® A 200+ was successfully tested and passed the strengthens electronic manufacturing industry standards:

- Visual cleanliness in accordance with IPC-610A
- Ionic cleanliness in accordance with J-STD 001D
- Surface tension in accordance with IPC-TM 650 and DIN 32513
- Solderability according to J-STD 003

Alternative product recommendation:

For water-based defluxing of electronic assemblies in high pressure spray-in-air processes we also recommend VIGON® A 201.